

PCN Number:	PCN20130326000		PCN Date:	03/28/2013	
Title:	Transfer of select devices in the .35um-UMC-F8J process to UMC-F8E Wafer Fab Facility				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept: Quality Services	
Proposed 1st Ship Date:	06/28/2013	Estimated Sample Availability:	Date provided at sample request.		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input checked="" type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

This notification is to announce the transfer of select devices in the .35um-UMC-F8J process to UMC-F8E Wafer Fab Facility.

Currently Qualified Sites, process, wafer dia.	Additional Sites, process, wafer dia.
UMC-F8J, .35um-UMC-F8J Process, 200mm	UMC-F8E, 0.35 DPQM Process, 200mm

Reason for Change:

Continuity of supply due to site shutdown

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
UMC-F8J	U8J	JPN

New

Chip Site	Chip site code (20L)	Chip country code (21L)
UMC-F8E	U8E	TWN

Sample product shipping label (not actual product label)

 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750	 	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS
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Product Affected:			
PCM1606E	PCM1742EG4	PCM1748KE/2KG4	PCM1754DBQG4
PCM1606E/2K	PCM1742KE	PCM1748KEG4	PCM1754DBQR
PCM1606E/2KG4	PCM1742KE/2K	PCM1753DBQ	PCM1754DBQRG4
PCM1606EG	PCM1742KE/2KG4	PCM1753DBQG4	PCM1755DBQ
PCM1606EG/2K	PCM1742KEG4	PCM1753DBQR	PCM1755DBQG4
PCM1606EG/2KE6	PCM1748E	PCM1753DBQR-S2	PCM1755DBQR
PCM1606EG4	PCM1748E/2K	PCM1753DBQR-S2G4	PCM1755DBQR/2354
PCM1606EGE6	PCM1748E/2KG4	PCM1753DBQRG4	PCM1755DBQRG4
PCM1742E	PCM1748EG4	PCM1754DBQ	
PCM1742E/2K	PCM1748KE	PCM1754DBQ-P	
PCM1742E/2KG4	PCM1748KE/2K	PCM1754DBQ-PG4	

Qualification Plan:				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qualification Device 1: PCM1753TDBQRQ1				
Wafer Fab Site:	UMC-F8E	Wafer Fab Process:	0.35 DPTM	
Wafer Diameter:	200mm			
Qualification Schedule:	Start:	03/2013	End:	End of 06/2013
Qualification:	<input checked="" type="checkbox"/> Plan <input type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size/Fails Lot#1 Lot#2 Lot#3		
High Temp Operating Life	140C(480 Hrs)	77/0	77/0	77/0
Electrical Characterization	-	Comp	Comp	Comp
**High Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/+150C (500 Cycles)	77/0	77/0	77/0
ESD CDM	250V	3/0	3/0	3/0
ESD HBM	1000V	3/0	3/0	3/0
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0
Bond Pull	76 Wire, 3 units min	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
Latch-up	(Per JESD78)	6/0	6/0	6/0
** Preconditioning sequence: (Level 3/260C)				

Qualification Device 2: PCM3168ATPAPRQ1					
Wafer Fab Site:	UMC-F8E	Wafer Fab Process:	0.35 DPTM		
Wafer Diameter:	200mm				
Qualification: <input checked="" type="checkbox"/> Plan <input type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size/Fails			
		Lot#1	Lot#2	Lot#3	
High Temp Operating Life	125C(1000 Hrs)	77/0	77/0	77/0	
Electrical Characterization	-	Comp	Comp	Comp	
**High Temp. Storage Life	150C(1000Hrs)	77/0	77/0	77/0	
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0	
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
**Temp Cycle	-65C/+150C (500 Cycles)	77/0	77/0	77/0	
ESD CDM	250V	3/0	3/0	3/0	
ESD HBM	1000V	3/0	3/0	3/0	
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0	
Bond Pull	76 Wire, 3 units min	76/0	76/0	76/0	
Die Shear	-	10/0	10/6	10/0	
Latch-up	(Per JESD78)	6/0	6/0	6/0	
** Preconditioning sequence: (Level 3/260C)					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com